

SPECIFICATION SHEET

MHZ SMD CRYSTAL CERAMIC COVER 2 PADS XP SERIES

SPECIFICATION SHEET NO.	S0102 - XP14M74560S412					
ORIGINAL MFG/PART NO.	TGS Crystals/CMG632 14M7456A30-12-30-40-60TLH					
NEXTGEN PART CODE	XP14M74560S412	Indicate This Code For <u>RFQ/</u> Order				
DATE	Jan. 2, 2025					
REVISION	A1 Updated With Most Recent Data					
DESCRIPTION AND	MHz SMD Crystal Glass seal, Ceramic Cover, 6035 Type, 2 pads, XP Series					
MAIN PARAMETRICS	Frequency stability ±30p ESR 60 ohm Max, Reflow Package in Tape/Reel, 10	±30ppm, Load Capacitor 12pF pm; Operating Temp. Range -40°C ~+85°C, Profile Condition 260 °C Max.				
CUSTOMER						
CUSTOMER PART NUMBER						
CROSS REF. PART NUMBER						
ΜΕΜΟ						

VENDOR APPROVE			
Issued/Checked/Approved	Compose Compose Compose Xu Xu	Compose Suby Chang Compose Suby Chang Compose Suby Chang Compose Suby Chang Compose Suby Chang Suby Compose Suby Suby Compose Suby Suby Compose Suby Suby Suby Suby Suby Suby Suby Suby	Jack Zhang Jack
Effective Date: Jan. 2, 2025			

Date:

1/2/2025

NextGen Components, Inc.

CUSTOMER APPROVE



MAIN FEATURE

- MHz SMD Crystal, 6035 Type, L6.0*W3.5*H1.2mm, 2 pads
- Glass seal, Ceramic Cover
- Low cost, High precision, High frequency stability.
- Low Profile and Short Lead time
- RoHS/RoHS III Compliant, RoHS Annex III Lead Exemption

(exempt per RoHS EU 2015/863)

- Moist are Sensitivity Level (MSL) Level 1
- Excellent Aging and Wide Frequency Range

APPLICATION

- Bluetooth, wireless communication set
- Communication Electronics

ELECTRICAL CHARACTERISTICS

- See Page 5 ~ Page 13 For Different Part Code And Rated Voltage.
- All Products Parameters are Subject To NextGen Components' Final Confirmation.



Image shown is a representation only. Exact specifications should be obtained from the product dimension.





HOW TO ORDER

• Please Follow Up Part Code Guide And Indicate NextGen Part Code <u>XP14M74560S412</u> For RFQ and Order.

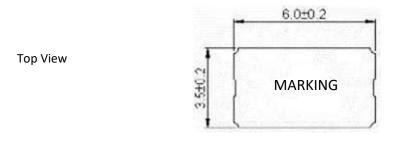
PART CODE GUIDE



CODE	NAME	KEY SPECIFICATION OPTION
ХР	Series Code	MHz SMD Crystal Glass seal, Ceramic Cover, 6035 Type, 2 pads
14M7456	Frequency Range Code	14M7456: 14.7456MHz or Custom Frequency Range by Page 6~ Page 13
OS	Internal Control Code	Letter A~Z, a~z or digits (0~9)
412	Parameters code	Special Parameters Code Letter A~Z, a~z or digits (1-9)
()	Special/Custom Parameters Code	Blank: N/A XX: Letter A~Z, a~z or digits (0~9) for Special/Custom Parameters



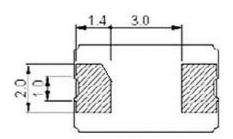
DIMENSION (Unit: Inch/mm)



Side View



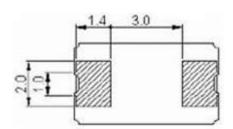
Bottom View



Connection #1 Crystal #2 Crystal

or

Alternative Case Bottom View





GENERAL SPECIFICATION

DADAMETED	SVMDOL	VALUE			LINUT	CONDITION
PARAMETER	SYMBOL	MIN.	TYPE	MAX.	UNIT	
Frequency Range	FO	8.0000	-	54.000	MHz	Customer specified
Mode of Vibration Code			Fundame	ental	1	Optional: 3rd OT Or 5th OT
Frequency Tolerance	∆F/F0	±10	±30	±50	ppm	at 25°C±3°C
Load Capacitance	CL	4	18	Series	pF	Customer specified
Frequency Stability	Тс	±10	±30	±50	ppm	Customer specified
Operating Temp. Range	TOPR	-40	-	+85	°C	Standard
Storage Temp. Range	Тѕтб	-55	-	+125	°C	
Equivalent Series Resistance	ESR		See Table 1		Ω	Customer specified
Drive Level	DL	-	100	200	μW	
Insulation Resistance	IR	500	-		mΩ	At 100VDC
Shunt Capacitance	CO	-	-	5.0	pF	
Aging per year	Fa	-3	-	+3	ppm	1st Year

Table 1

FREQUENCY RANGE	MODE OF VIBRATION	ESR (Ω) MAX
8.00000MHz≤ F0 <10.000MHz	Fundamental	150
10.000MHz≤ F0 <20.000MHz	Fundamental	60
20.000MHz≤ F0 <30.000MHz	Fundamental	40
30.000MHz≤ F0 <54.000MHz	Fundamental	30



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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

PART CODE	FREQUENCY RANGE	FREQUENCY TOLERANCE	LOAD CAPACITANCE	FREQUENCY STABILITY	OPERATING TEMPE. RANGE	EQUIVALENT SERIES RESISTANCE
	MHz	ppm	pF	ppm	°C	Ω Max.
XP8M000000S408	8.00000	±30	8	±30	-40 ~+85	150
XP8M000000S410	8.00000	±30	10	±30	-40 ~+85	150
XP8M000000S412	8.00000	±30	12	±30	-40 ~+85	150
XP8M000000S416	8.00000	±30	16	±30	-40 ~+85	150
XP8M0000005418	8.00000	±30	18	±30	-40 ~+85	150
XP8M0000005420	8.00000	±30	20	±30	-40 ~+85	150
XP8M192000S408	8.19200	±30	8	±30	-40 ~+85	150
XP8M192000S410	8.19200	±30	10	±30	-40 ~+85	150
XP8M192000S412	8.19200	±30	12	±30	-40 ~+85	150
XP8M192000S416	8.19200	±30	16	±30	-40 ~+85	150
XP8M192000S418	8.19200	±30	18	±30	-40 ~+85	150
XP8M192000S420	8.19200	±30	20	±30	-40 ~+85	150
XP9M216000S408	9.21600	±30	8	±30	-40 ~+85	150
XP9M216000S410	9.21600	±30	10	±30	-40 ~+85	150
XP9M216000S412	9.21600	±30	12	±30	-40 ~+85	150
XP9M216000S416	9.21600	±30	16	±30	-40 ~+85	150
XP9M216000S418	9.21600	±30	18	±30	-40 ~+85	150
XP9M216000S420	9.21600	±30	20	±30	-40 ~+85	150
XP9M830400S408	9.83040	±30	8	±30	-40 ~+85	150
XP9M830400S410	9.83040	±30	10	±30	-40 ~+85	150

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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

PART CODE	FREQUENCY RANGE MHz	FREQUENCY TOLERANCE ppm	LOAD CAPACITANCE pF	FREQUENCY STABILITY ppm	OPERATING TEMPE. RANGE °C	EQUIVALENT SERIES RESISTANCE Ω Max.
XP9M830400S412	9.83040	±30	12	±30	-40 ~+85	150
XP9M830400S416	9.83040	±30	16	±30	-40 ~+85	150
XP9M830400S418	9.83040	±30	18	±30	-40 ~+85	150
XP9M830400S420	9.83040	±30	20	±30	-40 ~+85	150
XP10M00000S408	10.00000	±30	8	±30	-40 ~+85	60
XP10M00000S410	10.00000	±30	10	±30	-40 ~+85	60
XP10M00000S412	10.00000	±30	12	±30	-40 ~+85	60
XP10M00000S416	10.00000	±30	16	±30	-40 ~+85	60
XP10M00000S418	10.00000	±30	18	±30	-40 ~+85	60
XP10M00000S420	10.00000	±30	20	±30	-40 ~+85	60
XP11M05920S408	11.05920	±30	8	±30	-40 ~+85	60
XP11M05920S410	11.05920	±30	10	±30	-40 ~+85	60
XP11M05920S412	11.05920	±30	12	±30	-40 ~+85	60
XP11M05920S416	11.05920	±30	16	±30	-40 ~+85	60
XP11M05920S418	11.05920	±30	18	±30	-40 ~+85	60
XP11M05920S420	11.05920	±30	20	±30	-40 ~+85	60
XP12M00000S408	12.00000	±30	8	±30	-40 ~+85	60
XP12M00000S410	12.00000	±30	10	±30	-40 ~+85	60
XP12M00000S412	12.00000	±30	12	±30	-40 ~+85	60
XP12M00000S416	12.00000	±30	16	±30	-40 ~+85	60

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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

	FREQUENCY	FREQUENCY	LOAD	FREQUENCY	OPERATING	EQUIVALENT
PART CODE	RANGE	TOLERANCE	CAPACITANCE	STABILITY	TEMPE.	SERIES
					RANGE	RESISTANCE
	MHz	ppm	pF	ppm	°C	Ω Max.
XP12M00000S418	12.00000	±20	18	±30	-40 ~+85	60
XP12M00000S420	12.00000	±30	20	±30	-40 ~+85	60
XP12M000S32418	12.00000	±30	18	±20	-40 ~+85	60
XP12M28800S408	12.28800	±30	8	±30	-40 ~+85	60
XP12M28800S410	12.28800	±30	10	±30	-40 ~+85	60
XP12M28800S412	12.28800	±30	12	±30	-40 ~+85	60
XP12M28800S416	12.28800	±30	16	±30	-40 ~+85	60
XP12M28800S418	12.28800	±30	18	±30	-40 ~+85	60
XP12M28800S420	12.28800	±30	20	±30	-40 ~+85	60
XP13M56000S408	13.56000	±30	8	±30	-40 ~+85	60
XP13M56000S410	13.56000	±30	10	±50	-40 ~+85	60
XP13M56000S412	13.56000	±30	12	±30	-40 ~+85	60
XP13M56000S416	13.56000	±30	16	±30	-40 ~+85	60
XP13M56000S418	13.56000	±30	18	±50	-40 ~+85	60
XP13M56000S420	13.56000	±30	20	±30	-40 ~+85	60
XP14M31818S408	14.31818	±30	8	±30	-40 ~+85	60
XP14M31818S410	14.31818	±30	10	±30	-40 ~+85	60
XP14M31818S412	14.31818	±30	12	±30	-40 ~+85	60
XP14M31818S416	14.31818	±30	16	±30	-40 ~+85	60
XP14M31818S418	14.31818	±30	18	±30	-40 ~+85	60

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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

PART CODE	FREQUENCY RANGE MHz	FREQUENCY TOLERANCE ppm	LOAD CAPACITANCE pF	FREQUENCY STABILITY ppm	OPERATING TEMPE. RANGE °C	EQUIVALENT SERIES RESISTANCE Ω Max.
XP14M318185420	14.31818	±30	20	±30	-40 ~+85	60
XP14M74560S408	14.74560	±30	8	±30	-40 ~+85	60
XP14M74560S410	14.74560	±30	10	±30	-40 ~+85	60
XP14M74560S412	14.74560	±30	12	±30	-40 ~+85	60
XP14M74560S416	14.74560	±30	16	±30	-40 ~+85	60
XP14M74560S418	14.74560	±30	18	±30	-40 ~+85	60
XP14M74560S420	14.74560	±30	20	±30	-40 ~+85	60
XP16M00000S408	16.00000	±30	8	±30	-40 ~+85	60
XP16M00000S410	16.00000	±30	10	±30	-40 ~+85	60
XP16M00000S412	16.00000	±30	12	±30	-40 ~+85	60
XP16M00000S416	16.00000	±30	16	±30	-40 ~+85	60
XP16M00000S418	16.00000	±30	18	±30	-40 ~+85	60
XP16M00000S420	16.00000	±30	20	±30	-40 ~+85	60
XP18M43200S408	18.43200	±30	8	±30	-40 ~+85	60
XP18M43200S410	18.43200	±30	10	±30	-40 ~+85	60
XP18M43200S412	18.43200	±30	12	±30	-40 ~+85	60
XP18M43200S416	18.43200	±30	16	±30	-40 ~+85	60
XP18M43200S418	18.43200	±30	18	±30	-40 ~+85	60
XP18M43200S420	18.43200	±30	20	±30	-40 ~+85	60
XP19M66080S408	19.66080	±30	8	±30	-40 ~+85	60

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PART CODE	FREQUENCY RANGE MHz	FREQUENCY TOLERANCE ppm	LOAD CAPACITANCE pF	FREQUENCY STABILITY ppm	OPERATING TEMPE. RANGE °C	EQUIVALENT SERIES RESISTANCE Ω Max.
XP19M66080S410	19.66080	±30	10	±30	-40 ~+85	60
XP19M66080S412	19.66080	±30	12	±30	-40 ~+85	60
XP19M66080S416	19.66080	±30	16	±30	-40 ~+85	60
XP19M66080S418	19.66080	±30	18	±30	-40 ~+85	60
XP19M66080S420	19.66080	±30	20	±30	-40 ~+85	60
XP20M00000S408	20.00000	±30	8	±30	-40 ~+85	40
XP20M00000S410	20.00000	±30	10	±30	-40 ~+85	40
XP20M00000S412	20.00000	±30	12	±30	-40 ~+85	40
XP20M00000S416	20.00000	±30	16	±30	-40 ~+85	40
XP20M00000S418	20.00000	±30	18	±30	-40 ~+85	40
XP20M00000S420	20.00000	±30	20	±30	-40 ~+85	40
XP22M11840S408	22.11840	±30	8	±30	-40 ~+85	40
XP22M11840S410	22.11840	±30	10	±30	-40 ~+85	40
XP22M11840S412	22.11840	±30	12	±30	-40 ~+85	40
XP22M11840S416	22.11840	±30	16	±30	-40 ~+85	40
XP22M11840S418	22.11840	±30	18	±30	-40 ~+85	40
XP22M11840S420	22.11840	±30	20	±30	-40 ~+85	40
XP24M00000S408	24.00000	±30	8	±30	-40 ~+85	40
XP24M00000S410	24.00000	±30	10	±30	-40 ~+85	40
XP24M00000S412	24.00000	±30	12	±30	-40 ~+85	40

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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

PART CODE	FREQUENCY RANGE MHz	FREQUENCY TOLERANCE ppm	LOAD CAPACITANCE pF	FREQUENCY STABILITY ppm	OPERATING TEMPE. RANGE °C	EQUIVALENT SERIES RESISTANCE Ω Max.
XP24M00000S416	24.00000	±30	16	±30	-40 ~+85	40
XP24M00000S418	24.00000	±30	18	±30	-40 ~+85	40
XP24M00000S420	24.00000	±30	20	±30	-40 ~+85	40
XP24M57600S408	24.57600	±30	8	±30	-40 ~+85	40
XP24M57600S410	24.57600	±30	10	±30	-40 ~+85	40
XP24M57600S412	24.57600	±30	12	±30	-40 ~+85	40
XP24M57600S416	24.57600	±30	16	±30	-40 ~+85	40
XP24M57600S418	24.57600	±30	18	±30	-40 ~+85	40
XP24M57600S420	24.57600	±30	20	±30	-40 ~+85	40
XP25M00000S408	25.00000	±30	8	±30	-40 ~+85	40
XP25M00000S410	25.00000	±30	10	±30	-40 ~+85	40
XP25M00000S412	25.00000	±30	12	±30	-40 ~+85	40
XP25M00000S416	25.00000	±30	16	±30	-40 ~+85	40
XP25M00000S418	25.00000	±30	18	±30	-40 ~+85	40
XP25M00000S420	25.00000	±30	20	±30	-40 ~+85	40
XP27M00000S408	27.00000	±30	8	±30	-40 ~+85	40
XP27M00000S410	27.00000	±30	10	±30	-40 ~+85	40
XP27M00000S412	27.00000	±30	12	±30	-40 ~+85	40
XP27M00000S416	27.00000	±30	16	±30	-40 ~+85	40
XP27M00000S418	27.00000	±30	18	±30	-40 ~+85	40

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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

PART CODE	FREQUENCY RANGE MHz	FREQUENCY TOLERANCE ppm	LOAD CAPACITANCE pF	FREQUENCY STABILITY ppm	OPERATING TEMPE. RANGE °C	EQUIVALENT SERIES RESISTANCE Ω Max.
XP27M00000S420	27.00000	±30	20	±30	-40 ~+85	40
XP28M63636S408	28.63636	±30	8	±30	-40 ~+85	40
XP28M63636S410	28.63636	±30	10	±30	-40 ~+85	40
XP28M63636S412	28.63636	±30	12	±30	-40 ~+85	40
XP28M63636S416	28.63636	±30	16	±30	-40 ~+85	40
XP28M63636S418	28.63636	±30	18	±30	-40 ~+85	40
XP28M63636S420	28.63636	±30	20	±30	-40 ~+85	40
XP30M00000S408	30.00000	±30	8	±30	-40 ~+85	30
XP30M00000S410	30.00000	±30	10	±30	-40 ~+85	30
XP30M00000S412	30.00000	±30	12	±30	-40 ~+85	30
XP30M00000S416	30.00000	±30	16	±30	-40 ~+85	30
XP30M00000S418	30.00000	±30	18	±30	-40 ~+85	30
XP30M00000S420	30.00000	±30	20	±30	-40 ~+85	30
XP32M00000S408	32.00000	±30	8	±30	-40 ~+85	30
XP32M00000S410	32.00000	±30	10	±30	-40 ~+85	30
XP32M00000S412	32.00000	±30	12	±30	-40 ~+85	30
XP32M00000S416	32.00000	±30	16	±30	-40 ~+85	30
XP32M00000S418	32.00000	±30	18	±30	-40 ~+85	30
XP32M000005420	32.00000	±30	20	±30	-40 ~+85	30
XP40M00000S408	40.00000	±30	8	±30	-40 ~+85	30

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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

PART CODE	FREQUENCY RANGE	FREQUENCY	LOAD CAPACITANCE	FREQUENCY STABILITY	OPERATING TEMPE. RANGE	EQUIVALENT SERIES RESISTANCE
	MHz	ppm	pF	ppm	°C	Ω Max.
XP40M00000S410	40.00000	±30	10	±30	-40 ~+85	30
XP40M00000S412	40.00000	±30	12	±30	-40 ~+85	30
XP40M00000S416	40.00000	±30	16	±30	-40 ~+85	30
XP40M00000S418	40.00000	±30	18	±30	-40 ~+85	30
XP40M00000S420	40.00000	±30	20	±30	-40 ~+85	30
XP48M00000S408	48.00000	±30	8	±30	-40 ~+85	30
XP48M00000S410	48.00000	±30	10	±30	-40 ~+85	30
XP48M00000S412	48.00000	±30	12	±30	-40 ~+85	30
XP48M00000S416	48.00000	±30	16	±30	-40 ~+85	30
XP48M00000S418	48.00000	±30	18	±30	-40 ~+85	30
XP48M00000S420	48.00000	±30	20	±30	-40 ~+85	30
XP50M00000S408	50.00000	±30	8	±30	-40 ~+85	30
XP50M00000S410	50.00000	±30	10	±30	-40 ~+85	30
XP50M00000S412	50.00000	±30	12	±30	-40 ~+85	30
XP50M00000S416	50.00000	±30	16	±30	-40 ~+85	30
XP50M00000S418	50.00000	±30	18	±30	-40 ~+85	30
XP50M00000S420	50.00000	±30	20	±30	-40 ~+85	30

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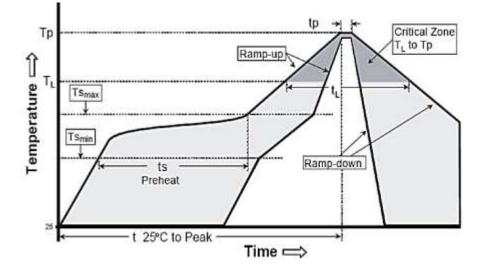


RELIABILITY (MECHANICAL AND ENVIRONMENTAL ENDURANCE)

TEST ITEMS	TEST METHOD AND CONDITIONS	REQUIREMENTS
High Temperature High Humidity Storage	Temperature: 85°C±3°C Relative Humidity:85%RH Time: 96 Hours	JIS C5023
High Temperature Storage	Temperature: 125°C±3°C Time: 96 Hours.	MIL-STD-883E Method 1005.8
Low Temperature Storage	Temperature: -40°C±3°C Time: 96 Hours.	MIL-STD-883E Method 1013
Thermal Shock	Temperature 1: -55°C±5°C Temperature 2: 85°C±5 °C Temperature change between T1 and T2 5 min 10cycles maintain T1 and T2 for 30 minutes each cycle	MIL-STD-202F Method 107 Condition A
Resistance to Solder Heat	Solder Temperature: 260°C±5°C Time: 10±1 Seconds	MIL-STD-202F Method 210E
Solderability	The solder pot temperature is 245±5°C , dwell time 5±0.5sec	J-STD-002B
Drop Test	3 Times Free Fall from 50cm height table to 3cm thickness hard wood board	J-STD-002B
Mechanical Shock	Half sine wave,1000 G 3 Times for all 3 directions(X,Y Z)	MIL STD 202F Method 213B
Vibration	Frequency Range: 10Hz ~ 55Hz Amplitude: 0.75mm 2 Hours in each direction, total 6 Hours	MIL-STD-883E Method 2007.3
Leakage Test	Take measurements with a helium Leakage detector Leakage Rate≤1×10 ⁻³ Pa cm³/s	MIL-STD-883E



SUGGESTED REFLOW PROFILE (For Reference Only)



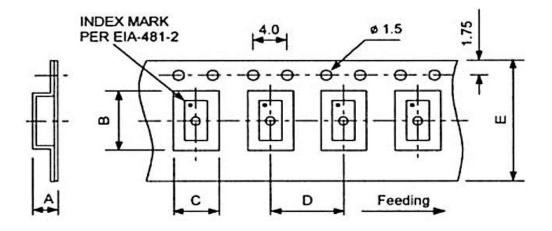
PROFILE FEATURE		PB-FREE ASSEMBLY	
Average Ramp-up Rate (Ts Max to Tp)		3°C/second Max	
Preheat	Temperature Min (Ts Min.)	125°C	
	Temperature Max (Ts Max.)	200°C	
	Time (ts Min. to ts Max.)	60 ~ 180 seconds	
Time maintained above	Temperature (TL)	217°C	
	Time (tL)	60 ~ 150 seconds	
Peak/Classification Temperature (Tp)		260 °C	
Time within 5°C of actual Peak Temperature (tp)		20 ~ 40 seconds	
Ramp-down rate		6 °C /Second Max.	
Time 25 °C to Peak Temperature		8 minutes Max.	
Suggest reflow times		3 Times Max.	

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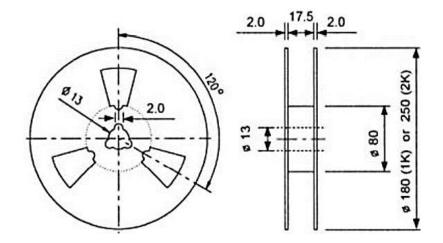


TAPE AND REEL (1000pcs/Reel, Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-2 and specifications., 1000pcs/Reel



ITEM	DIMENSION	
A	1.70	
В	5.45	
С	3.65	
D	8.00	
E	12.0	



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IMPORTANT NOTES AND DISCLAIMER

- ROHS COMPLIANCE: The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for this product can be obtained can be obtained at Download Center.
- REACH COMPLIANCE: REACH substances of high concern (SVHCs) information is available for this product.
 Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained can be obtained at Download Center.
- All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
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